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(12) United States Design Patent
Mueller

(10) **Patent No.:** **US D660,810 S**
(45) **Date of Patent:** ** **May 29, 2012**

(54) **HEAT SPREADER WITH FINS FOR A COMPUTER MEMORY MODULE**

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(73) Assignee: **Corsair Memory, Inc.**, Fremont, CA (US)

(**) Term: **14 Years**

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(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/179**
(58) **Field of Classification Search** D13/179;
165/80.3, 104.26, 104.33, 122, 151, 185;
257/706, 707, 718–722; 361/695, 697, 700,
361/702, 704, 709, 710, 711, 719
See application file for complete search history.

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(Continued)

Primary Examiner — Selina Sikder
(74) *Attorney, Agent, or Firm* — Reed Smith LLP

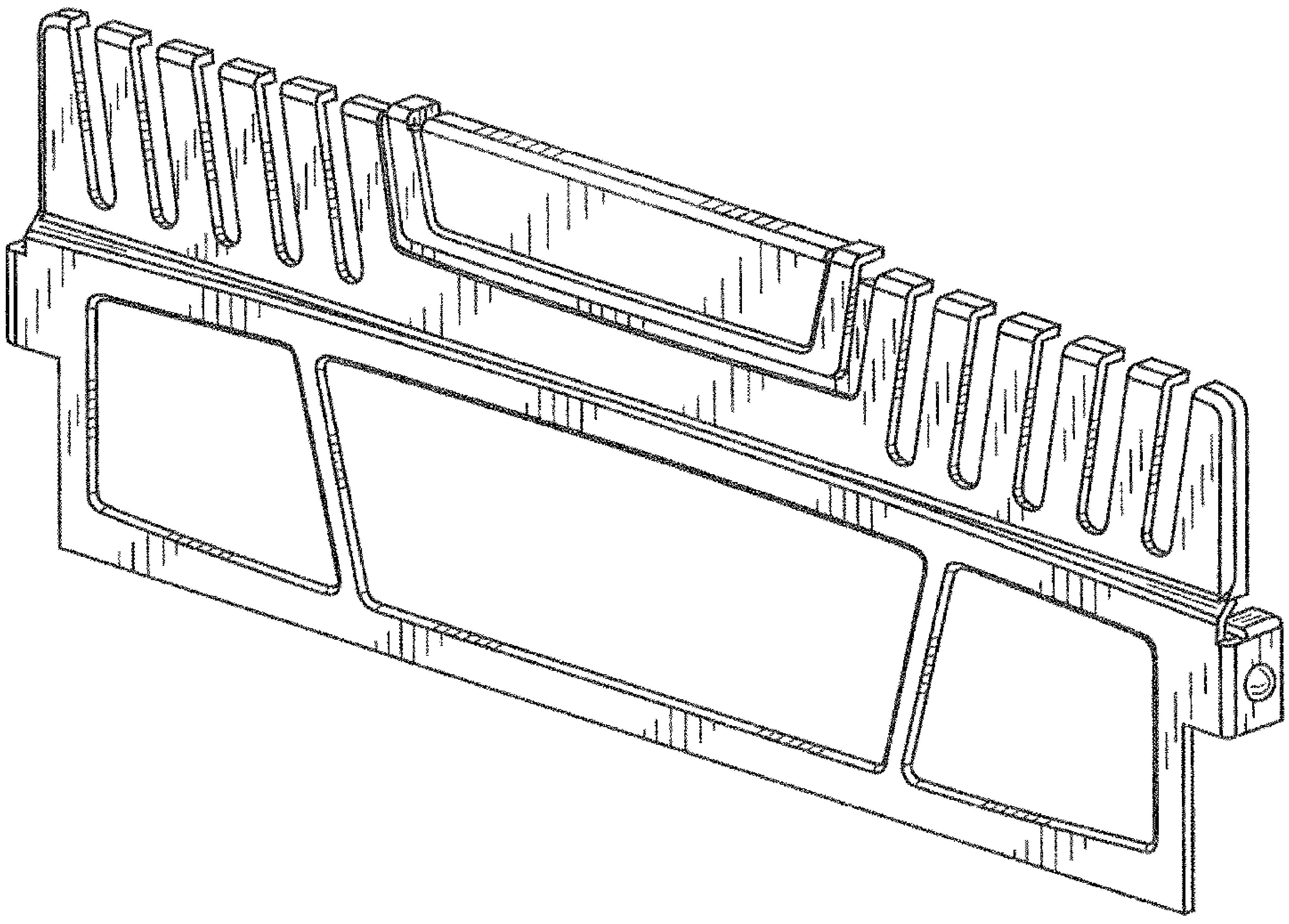
(57) **CLAIM**

The ornamental design for a heat spreader with fins for a computer memory module, as shown and described.

DESCRIPTION

FIG. **1** is a front right side perspective view of a first embodiment of a heat spreader with fins for a computer memory module showing our design;
FIG. **2** is a front view of the first embodiment of the heat spreader with fins for a computer memory module;
FIG. **3** is a rear view of the first embodiment of the heat spreader with fins for a computer memory module;
FIG. **4** is a top side view of the first embodiment of the heat spreader with fins for a computer memory module;
FIG. **5** is a bottom side view of the first embodiment of the heat spreader with fins for a computer memory module;
FIG. **6** is a right side view of the first embodiment of the heat spreader with fins for a computer memory module;
FIG. **7** is a left side view of the first embodiment of the heat spreader with fins for a computer memory module;
FIG. **8** is a front right side perspective view of a second embodiment of the heat spreader with fins for a computer memory module;
FIG. **9** is a front view of the second embodiment of the heat spreader with fins for a computer memory module;
FIG. **10** is a rear view of the second embodiment of the heat spreader with fins for a computer memory module;
FIG. **11** is a top side view of the second embodiment of the heat spreader with fins for a computer memory module;
FIG. **12** is a bottom side view of the second embodiment of the heat spreader with fins for a computer memory module;
FIG. **13** is a right side view of the second embodiment of the heat spreader with fins for a computer memory module; and,
FIG. **14** is a left side view of the second embodiment of the heat spreader with fins for a computer memory module.
The shade lines in the figures show contour and not surface ornamentation.

1 Claim, 10 Drawing Sheets



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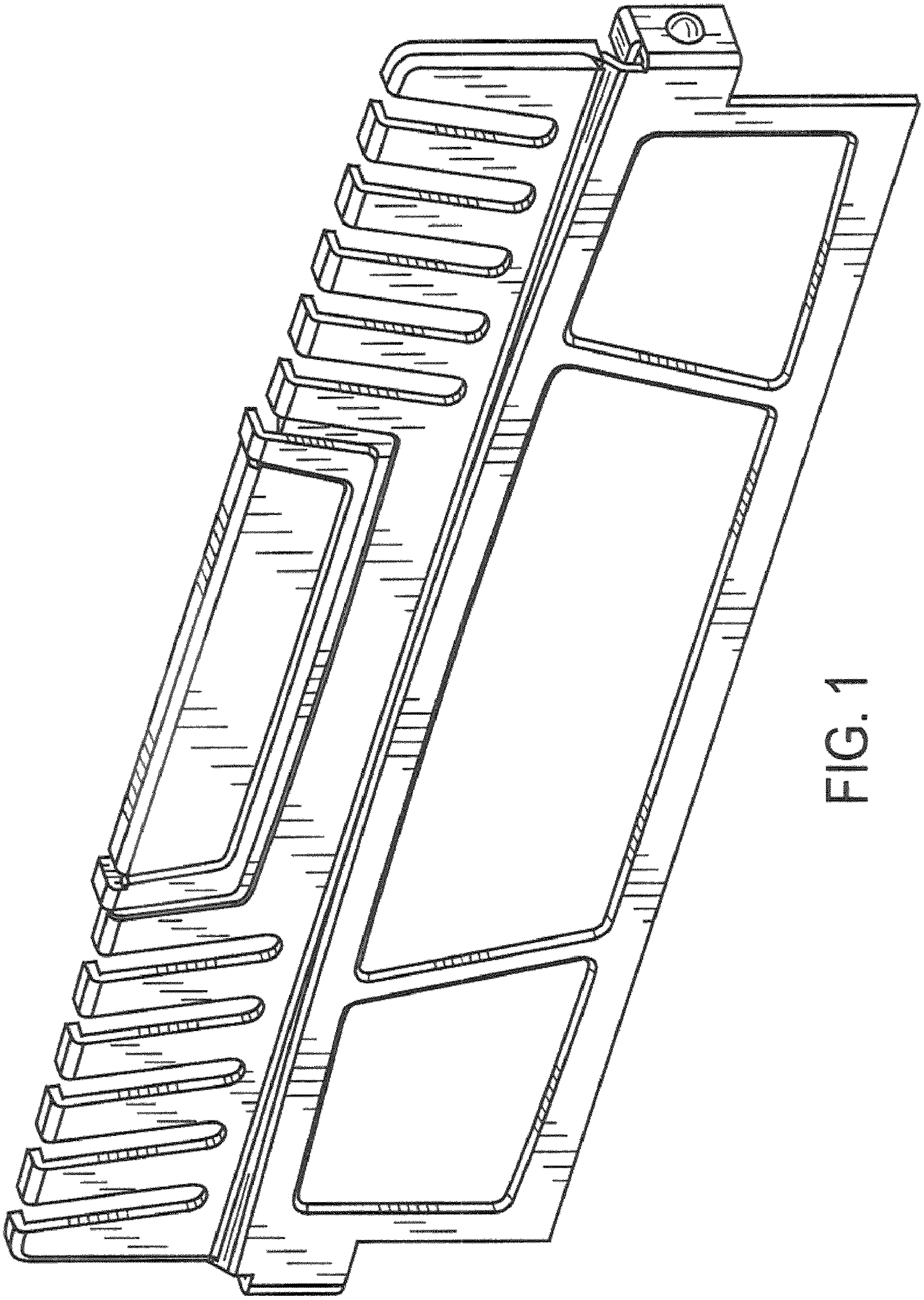

FIG. 1

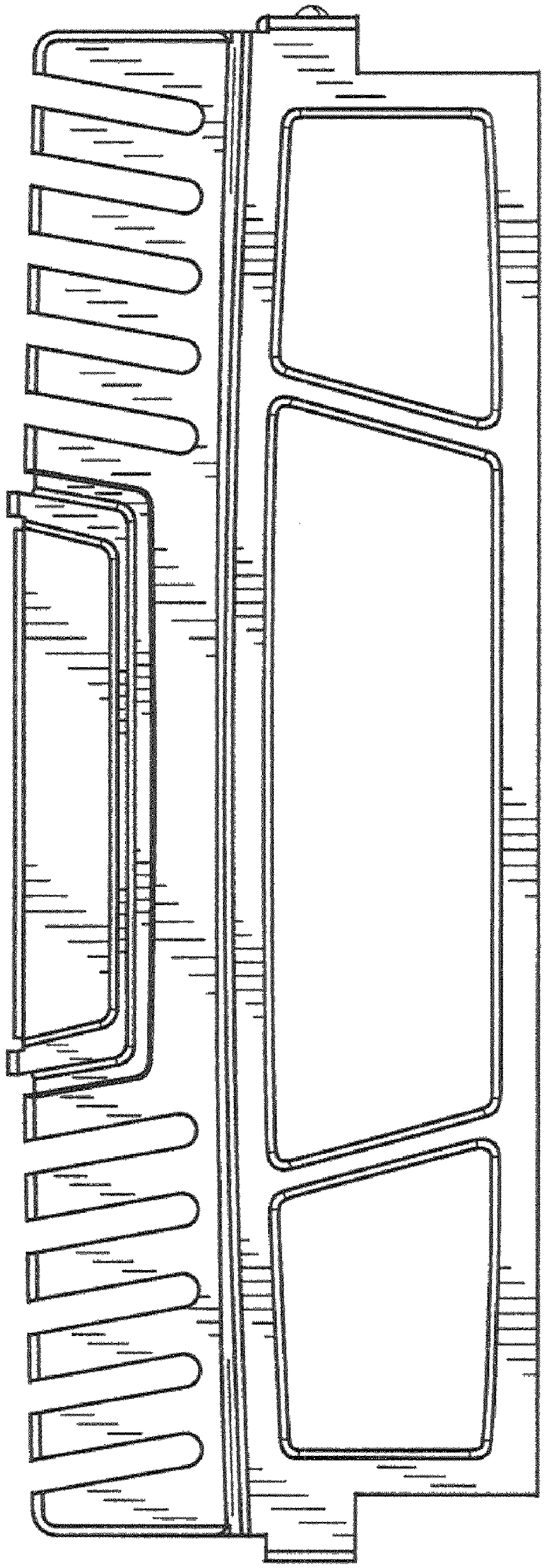

FIG. 2

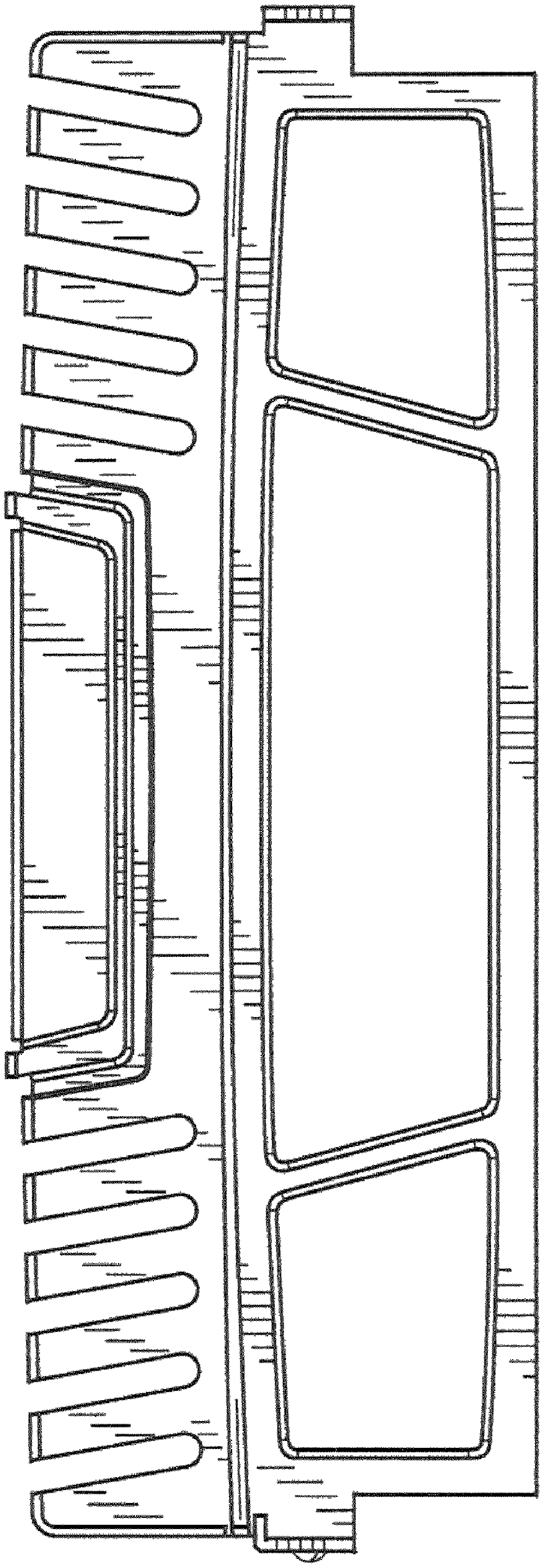

FIG. 3

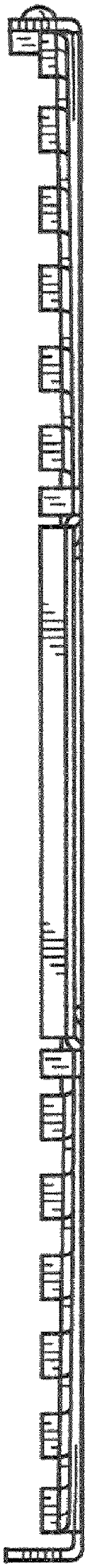

FIG. 4

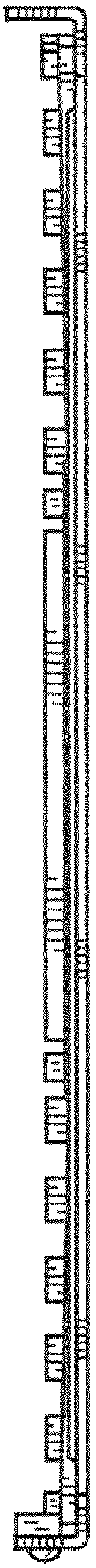

FIG. 5

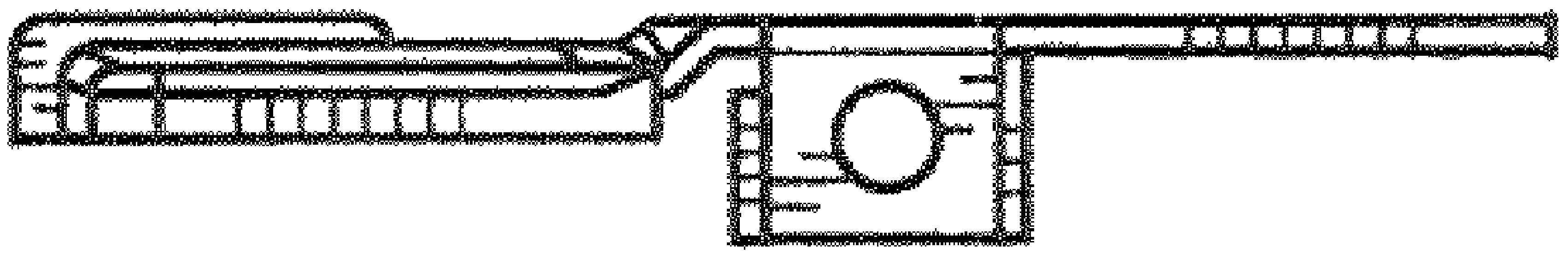

FIG. 7

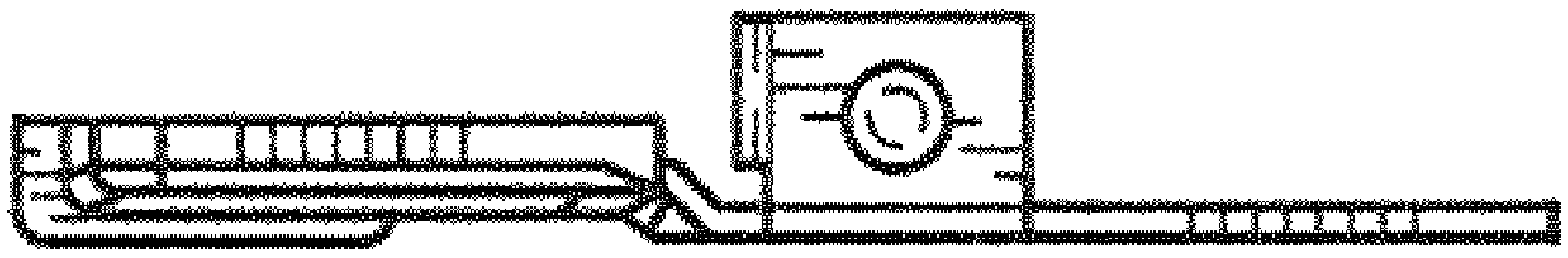

FIG. 6

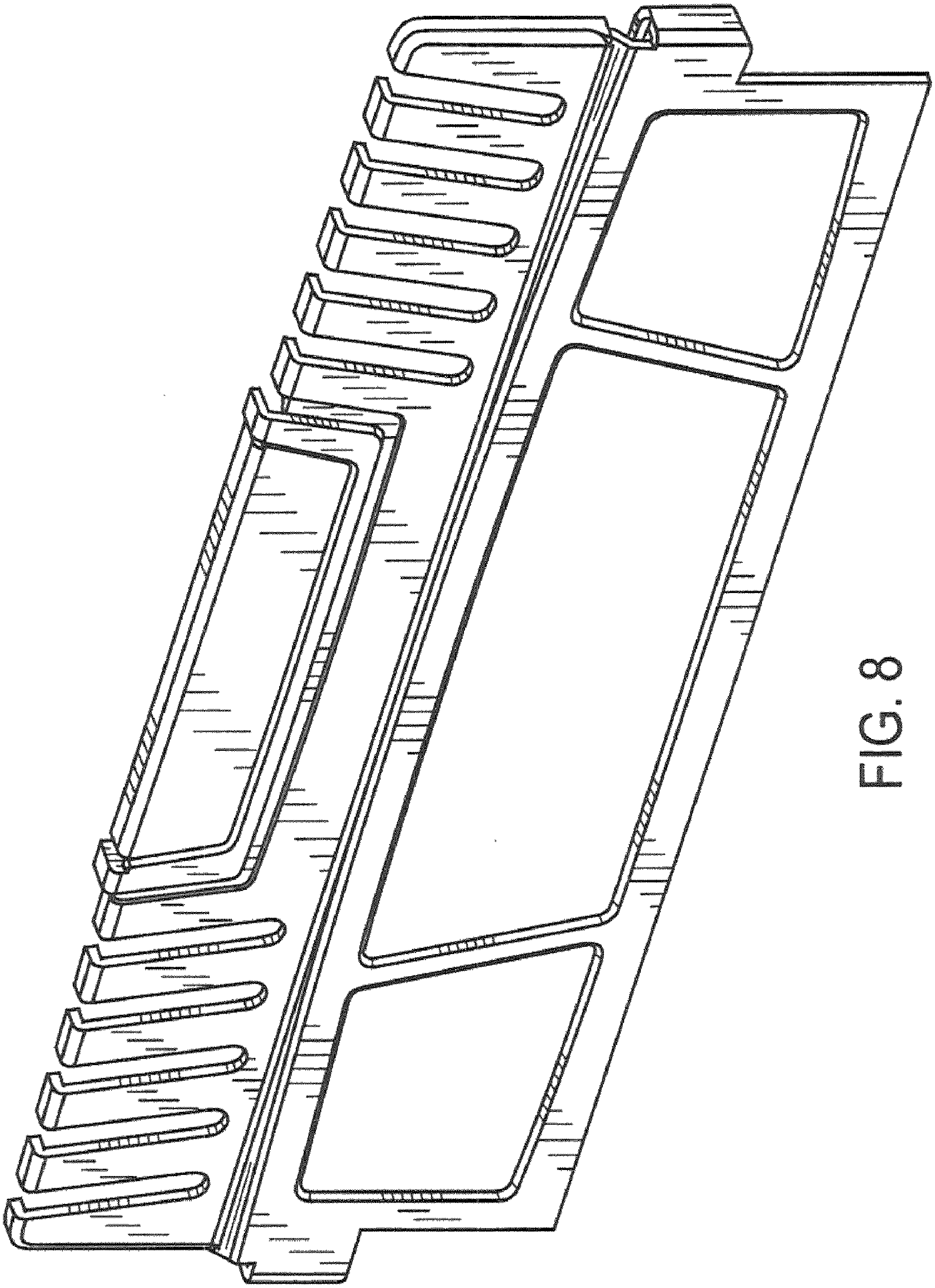

FIG. 8

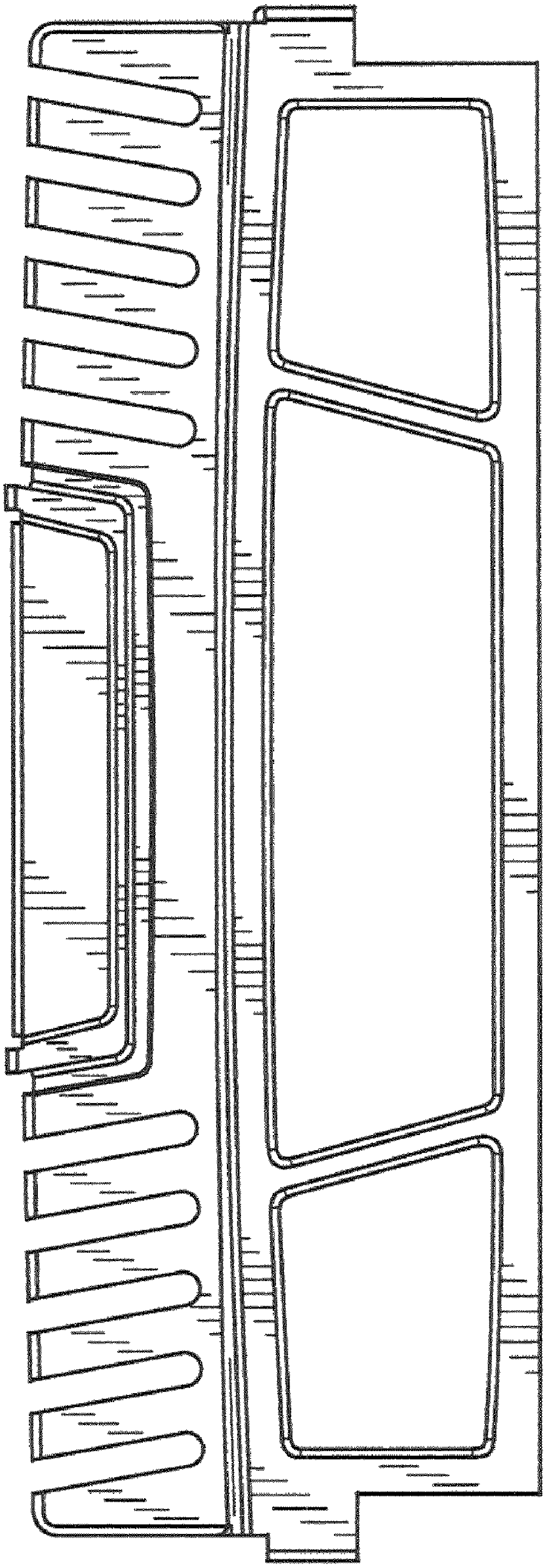

FIG. 9

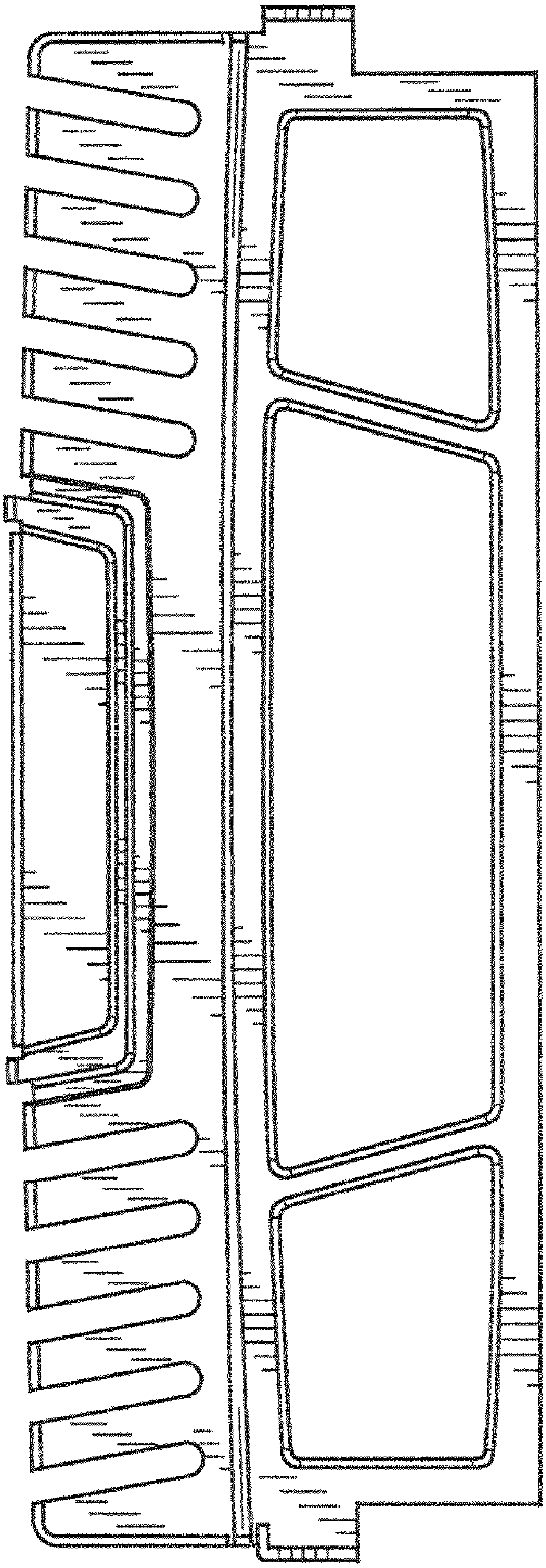

FIG. 10

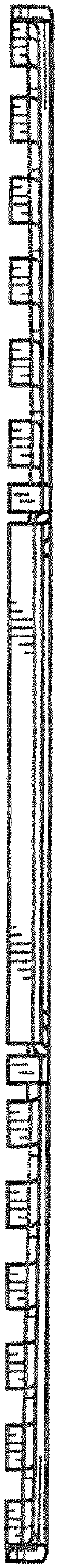

FIG. 11

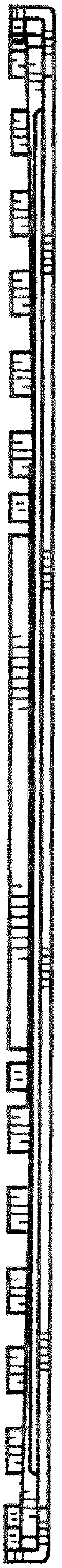

FIG. 12

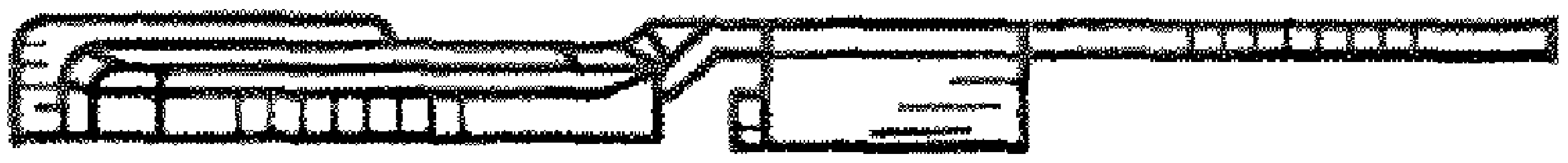

FIG. 14

FIG. 13